

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUNGRAE PARK	09/23/2014
WEI-SHENG LEI	09/23/2014
JAMES S. PAPANU	09/24/2014
BRAD EATON	09/25/2014
AJAY KUMAR	09/25/2014
RECEIVING PARTY DATA	
Name:	Applied Materials, Inc.
Street Address:	3050 Bowers Avenue
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14497027
CORRESPONDENCE DATA	
Fax Number:	(503)439-6073
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(503) 439-8778
Email:	lisa_puccinelli@bstz.com
Correspondent Name:	JUSTIN K. BRASK
Address Line 1:	1279 OAKMEAD PARKWAY
Address Line 4:	SUNNYVALE, CALIFORNIA 94085-4040
ATTORNEY DOCKET NUMBER:	4887.P1179
NAME OF SUBMITTER:	JUSTIN K. BRASK
SIGNATURE:	/Justin K. Brask/
DATE SIGNED:	09/25/2014
Total Attachments: 6	
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source=4887P1179_Assignments_09-25-14-#page6.tif

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we, the below-named inventor(s):

Jungrae Park; Wei-Sheng Lei; James S. Papanu; Brad Eaton; Ajay Kumar

hereby sell, assign, and transfer to:

Applied Materials, Inc.

a Corporation of Delaware, having a principal place of business at 3050 Bowers Avenue, Santa Clara, California 95054 United States ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions or improvements that are disclosed in the application (provisional or non-provisional) for the United States patent which for the non-provisional application may have a declaration executed by the undersigned prior hereto or concurrently herewith and which application (provisional or non-provisional) is entitled

HYBRID WAFER DICING APPROACH USING A PHASE MODULATED LASER BEAM PROFILE LASER SCRIBING PROCESS AND PLASMA ETCH PROCESS

said patent application also identified as follows (when known):

[I/we hereby authorize an attorney or agent for said Assignee to insert below the application number and filing date of said patent application when known.]

United States Patent Application Number **14/497,027** filed **September 25, 2014**

and in and to said application (provisional or non-provisional) and all provisional applications, non-provisional applications, utility applications, design applications, divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions or improvements; and in and to all original patents, reissued patents, reexamination certificates, and extensions, that have been or shall be issued in the United States and all foreign countries on said inventions or improvements, and in and to all rights of priority resulting from the filing of said United States application;

agree that said Assignee may apply for and receive a patent or patents for said inventions or improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all provisional applications, non-provisional applications, utility applications, design applications, divisional applications, continuation applications, continued prosecution applications, continuation-in-part applications, substitute applications, renewal applications, reissue applications, reexaminations, extensions, and all other patent applications on any and all said inventions or improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions or improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions or improvements and for vesting title to said inventions or improvements, and all applications for patents and all patents on said inventions or improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor: Please Sign and Date Below:

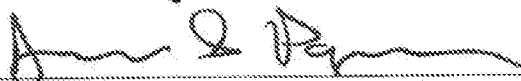
Date

Name: **Jungrae Park**

Date

Name: **Wei-Sheng Lei**

9/24/2014



Date

Name: **James S. Papanu**

Date

Name: **Brad Eaton**

Date

Name: **Ajay Kumar**

Date

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Date Name: Jungrae Park

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Date Name: Wei-Sheng Lei

Date Name: James S. Papanu

Date Name: Brad Eaton

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